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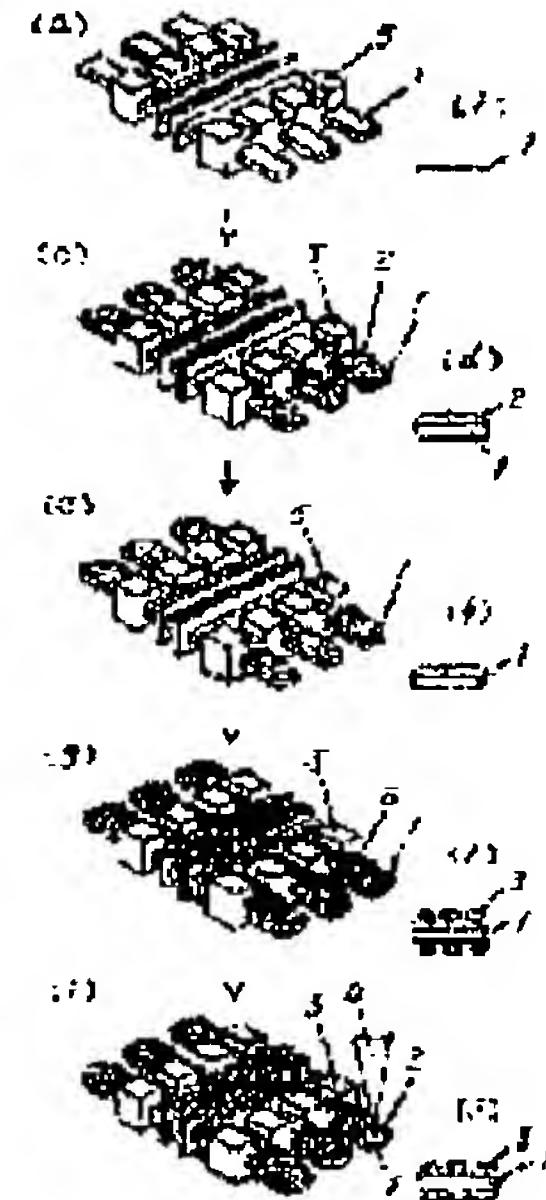
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## (54) SOLDER JOINT METHOD FOR INSULATED WIRE AND TERMINAL

## (57)Abstract:

**PROBLEM TO BE SOLVED:** To jointing a terminal and an insulated wire with solder uniformly and stably by winding the insulated wire around a solder-coated terminal and irradiating the wound part with a laser beam.

**SOLUTION:** A predetermined amount of cream solder 2 is discharged or coated onto a predetermined upper surface of a terminal 1. The solder 2 is heated with a hot plate to be temporarily melted. Thus, the surface of the solder 2 is made substantially uniform, so that the subsequent operation of winding an insulated wire 3 is facilitated. In addition, the absorbing rate of a laser beam 4 at the soldering surface is also made uniform during the irradiation of the beam 4 so that the solder joint is stabilized. Next, the wire 3 is wound around predetermined regions of a bobbin 5 and the terminal 1. Successively, the converged beam 4 is injected onto a predetermined surface of the terminal 1, whereby, while melting the solder 2 with the heat of the beam 4 and while destroying or melting the insulation sheath of the wire 3, the terminal 1 and the wound wire 3 are jointed with the solder. As a result, a uniform and stable solder joint can be obtained.



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